METHOD FOR ASSEMBLING TWO SUBSTRATES BY MOLECULAR ADHESION

Abstract

The invention relates to a method for assembly by molecular adhesion of two substrates, at least one of the two substrates being provided with a surface dielectric layer. The method comprises activating the surface dielectric layer by exposure to a plasma formed between two electrodes (4a, 4b) of an activation chamber (3), for an activation time of between 15 seconds and 2 minutes, during which a radiofrequency power is applied to one of the electrodes. The method comprises introducing into the activation chamber (3) a controlled flow of oxygen or nitrogen and a controlled flow of a gas comprising sulfur. The method is remarkable in that the radiofrequency power has a density strictly greater than 1.1 W/cm^2.

Fig. 4e